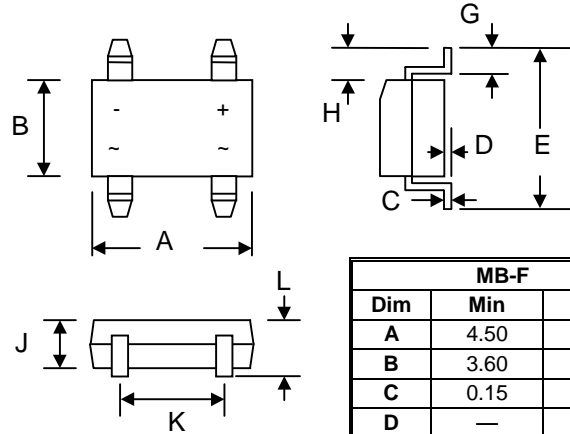


### Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Flammability 94V-O



MB-F		
Dim	Min	Max
A	4.50	4.95
B	3.60	4.10
C	0.15	0.35
D	—	0.20
E	6.40	7.00
G	0.50	1.10
H	1.30	1.70
J	1.20	1.60
K	2.30	2.70
L	—	1.80
All Dimensions in mm		

### Mechanical Data

- Case: MB-F, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.134 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- **Lead Free: For RoHS / Lead Free Version,**

### Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbo	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) @ $T_A = 40^\circ\text{C}$ Average Rectified Output Current (Note 2) @ $T_A = 40^\circ\text{C}$	$I_o$	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30							A
$I^2t$ Rating for Fusing ( $t < 8.3\text{ms}$ )	$I^2t$	5.0							$\text{A}^2\text{s}$
Forward Voltage per element @ $I_F = 0.5\text{A}$	$V_{FM}$	1.0							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	$I_{RM}$	5.0 500							$\mu\text{A}$
Typical Junction Capacitance per leg (Note 3)	$C_j$	13							pF
Typical Thermal Resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	60 16							$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with  $1.3\text{mm}^2$  solder pad.  
2. Mounted on aluminum substrate PC board with  $1.3\text{mm}^2$  solder pad.  
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

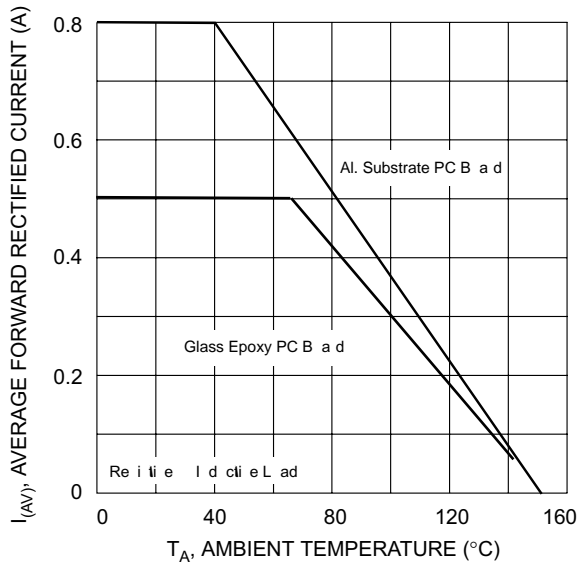


Fig. 1 O p t i c e i t De a t i g C e

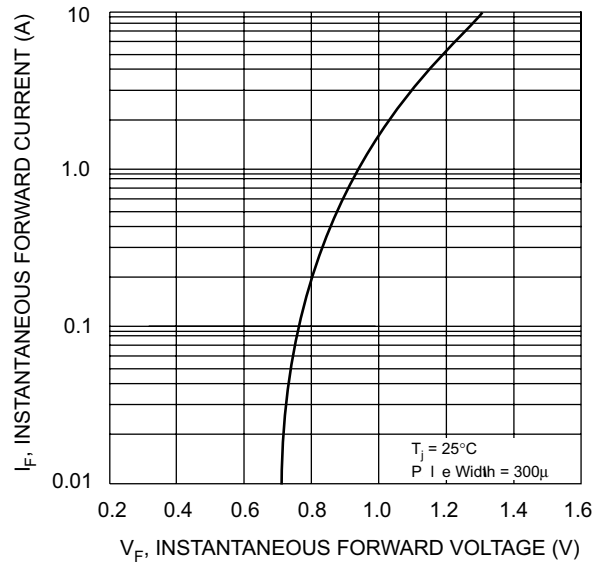


Fig. 2 T p i c a l F a d C h a c t e i t i c p e l e g

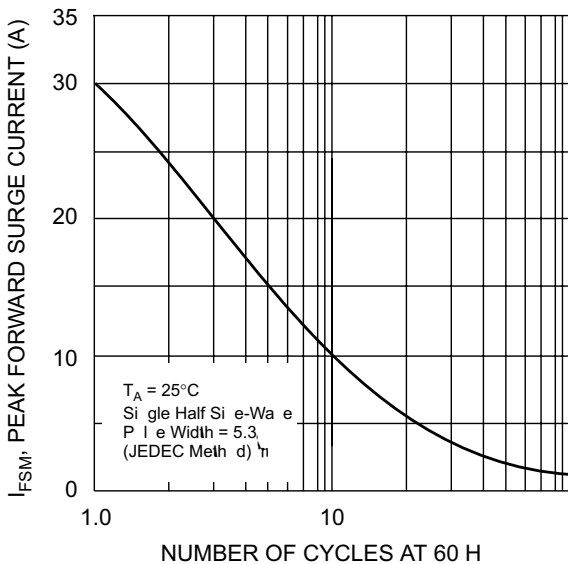


Fig. 3 M a i n Peak F a d S g e C e i p e l e g

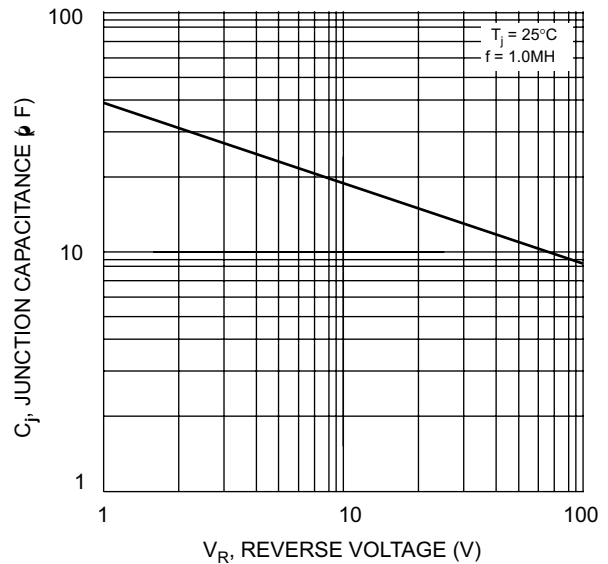


Fig. 4 T p i c a l J c t i C a p a c i t a c e

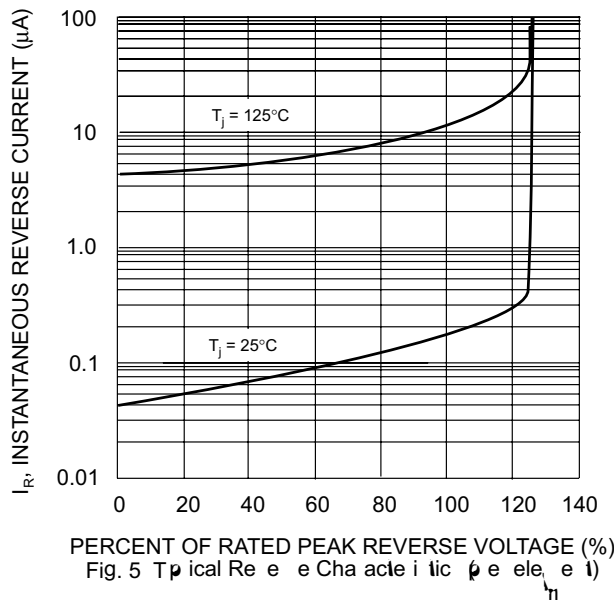


Fig. 5 T p i c a l R e e e C h a c t e i t i c p e e l e e t